Power MOSFET

40 V, 3.7 m Ω , 123 A, Single N–Channel DPAK

Features

- Low R_{DS(on)} to Minimize Conduction Losses
- MSL 1 @ 260°C
- 100% Avalanche Tested
- AEC Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parame	Symbol	Value	Unit		
Drain-to-Source Voltage			V _{DSS}	40	V
Gate-to-Source Voltage			V_{GS}	±20	V
Continuous Drain Cur-		T _C = 25°C	I _D	123	Α
rent (R _{θJC}) (Notes 1 & 3)		T _C = 85°C		95	
Power Dissipation (R _{θJC}) (Note 1)	Steady	T _C = 25°C	P _D	107	W
Continuous Drain Cur-	State	T _A = 25°C	I _D	24	Α
rent ($R_{\theta JA}$) (Notes 1, 2, 3)		T _A = 85°C		18.5	
Power Dissipation (R _{θJA}) (Notes 1 & 2)		T _A = 25°C	P _D	4.0	W
Pulsed Drain Current	t _p =10μs	T _A = 25°C	I _{DM}	400	Α
Current Limited by Package T _A = 25°C (Note 3)			I _{DmaxPkg}	100	Α
Operating Junction and S	T _J , T _{stg}	-55 to 175	°C		
Source Current (Body Di	I _S	100	Α		
Single Pulse Drain-to-S Energy (V_{GS} = 10 V, L = 46.2 A, R_{G} = 25 Ω)	E _{AS}	320	mJ		
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			T _L	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

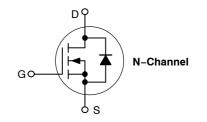
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- 3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and suty cycle.



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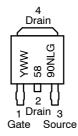
V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
40 V	3.7 m Ω @ 10 V	100 A
40 V	5.5 mΩ @ 4.5 V	123 A





MARKING DIAGRAMS & PIN ASSIGNMENT

STYLE 2



Y = Year WW = Work Week 5890NL = Device Code G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter		Value	Unit
Junction-to-Case (Drain)	$R_{ heta JC}$	1.4	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	37	

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•				•	•	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 250 μA		40			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				40		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	Voc = 0 V T _J = 25°C				1.0	μΑ
		$V_{GS} = 0 V$, $V_{DS} = 40 V$	T _J = 150°C			100	
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 V, V_{GS}$	= ±20 V			±100	nA
ON CHARACTERISTICS (Note 4)						•	
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 0$	= 250 μΑ	1.5		2.5	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				7.4		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$ $V_{GS} = 4.5 \text{ V}, I_D = 50 \text{ A}$			2.9	3.7	mΩ
					4.4	5.5	
Forward Transconductance	gFS	V _{DS} = 15 V, I _D = 15 A			16.3		S
CHARGES AND CAPACITANCES							
Input Capacitance	C _{iss}	V _{GS} = 0 V, f = 1.0 MHz, V _{DS} = 25 V			4760		pF
Output Capacitance	C _{oss}				580		
Reverse Transfer Capacitance	C _{rss}	55			385		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 15 V, I _D = 50 A			84		nC
Total Gate Charge	Q _{G(TOT)}				42		nC
Threshold Gate Charge	Q _{G(TH)}	$V_{GS} = 4.5 \text{ V}, V_{D}$	_S = 15 V,		4.2		
Gate-to-Source Charge	Q _{GS}	$I_D = 50$			13.7		
Gate-to-Drain Charge	Q_{GD}				18.8		
SWITCHING CHARACTERISTICS (Not	e 5)						
Turn-On Delay Time	t _{d(on)}	V_{GS} = 10 V, V_{DS} = 20 V, I_{D} = 50 A, R_{G} = 2.0 Ω			12		ns
Rise Time	t _r				35		
Turn-Off Delay Time	t _{d(off)}				38		
Fall Time	t _f				11		1

Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit	
DRAIN-SOURCE DIODE CHARACTERISTICS								
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V, I _S = 50 A	T _J = 25°C		0.86	1.2	V	
		V _{GS} = 0 V, I _S = 20 A	T _J = 25°C		0.78	1.0		
Reverse Recovery Time	t _{RR}	V_{GS} = 0 V, dls/dt = 100 A/ μ s, I_{S} = 50 A			35		ns	
Charge Time	ta				19		1	
Discharge Time	tb				16		1	
Reverse Recovery Charge	Q _{RR}				34		nC	

TYPICAL PERFORMANCE CURVES

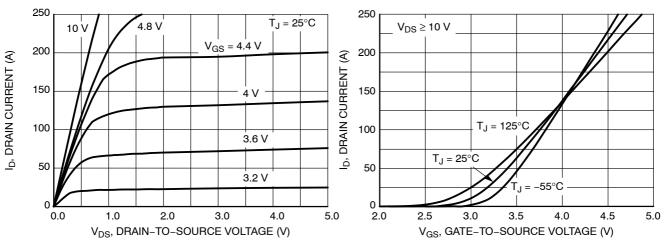


Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics

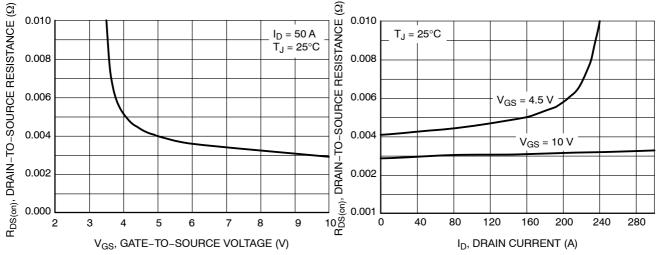


Figure 3. On-Resistance vs. Gate-to-Source Voltage

Figure 4. On-Resistance vs. Drain Current and Gate Voltage

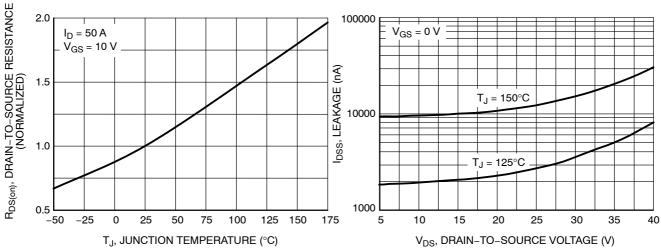


Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-to-Source Leakage Current vs. Drain Voltage

TYPICAL PERFORMANCE CURVES

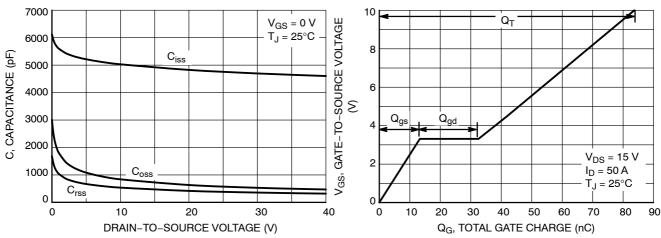


Figure 7. Capacitance Variation

Figure 8. Gate-To-Source Voltage vs.
Total Charge

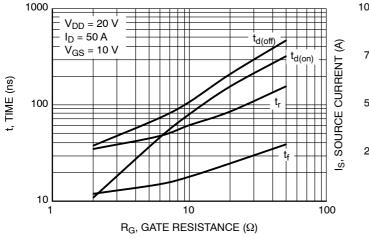


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

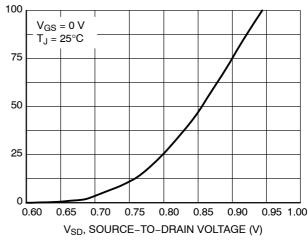


Figure 10. Diode Forward Voltage vs. Current

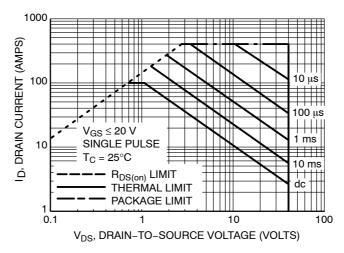


Figure 11. Maximum Rated Forward Biased Safe Operating Area

TYPICAL PERFORMANCE CURVES

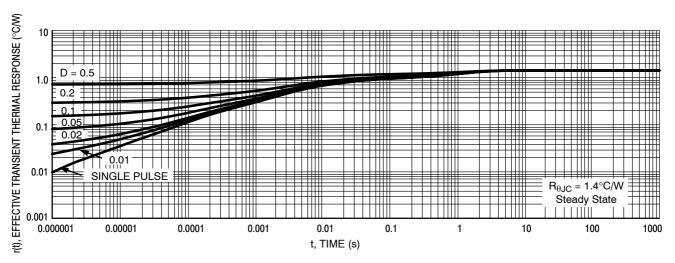


Figure 12. Thermal Response

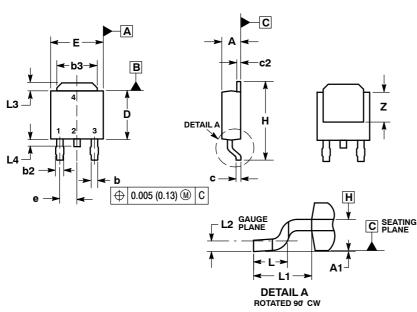
ORDERING INFORMATION

Order Number	Package	Shipping [†]
NVD5890NLT4G	DPAK (Pb-Free)	2500/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

DPAK CASE 369C ISSUE D

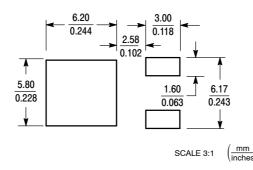


- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994
- 2. CONTROLLING DIMENSION: INCHES.
 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-
- MENSIONS b3, L3 and Z.

 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
 5. DIMENSIONS D AND E ARE DETERMINED AT THE
- OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 6. DATUMS A AND B ARE DETERMINED AT DATUM

	INCHES		MILLIN	LIMETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.030	0.045	0.76	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
E	0.250	0.265	6.35	6.73	
е	0.090	BSC	2.29	BSC	
Н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.108	REF	2.74 REF		
L2	0.020 BSC		0.51 BSC		
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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